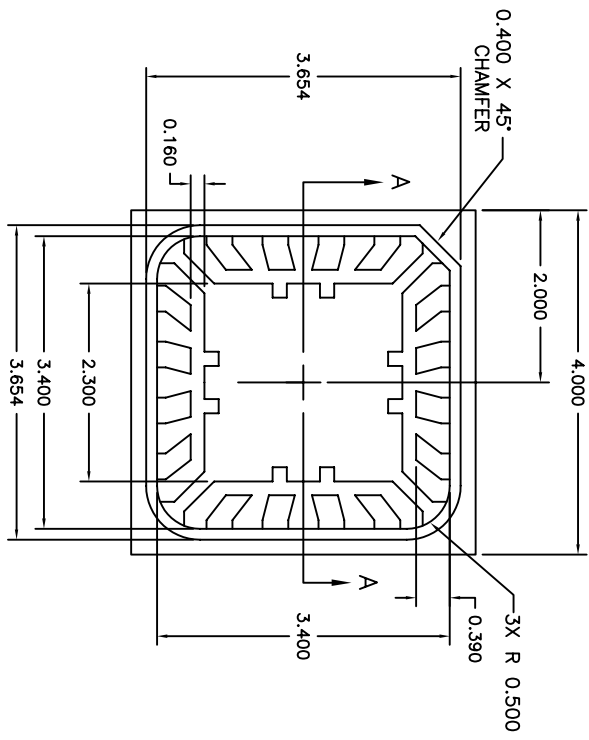


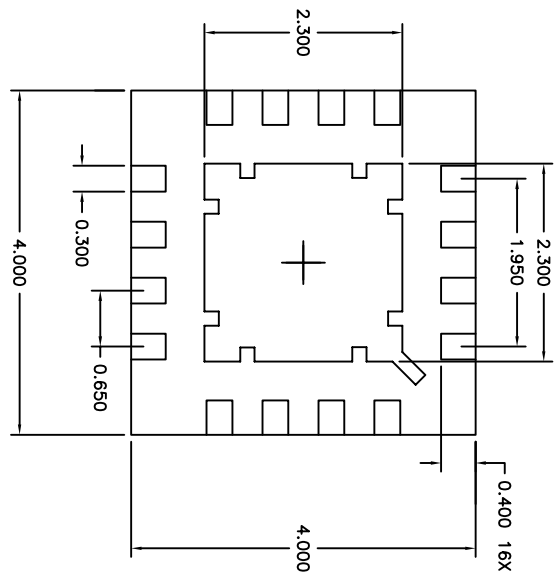
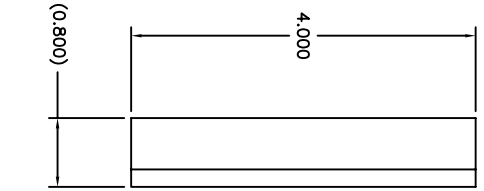
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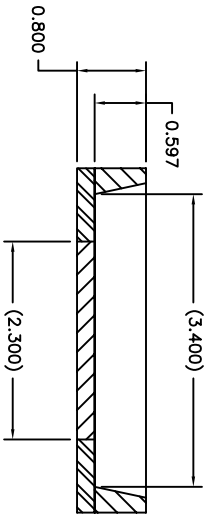
REVISIONS			APPROVED
EON NO.	DATE	DESCRIPTION	
10473	10/17/05	PRODUCTION RELEASE	D.BENAVANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FINISH: FULL GOLD PLATE.
 3. LEAD FRAME: COPPER, 194 FH.
 4. LEAD THICKNESS: 0.2030 ±.0076.
 5. FRAME THICKNESS: 2.300mm X 2.300mm.
 6. DIE PAD: 2.300mm X 2.300mm.
 7. JEDEC OUTLINE: MO-220 (VGGC-2)



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: XXXX ± 0.15 XXXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/17/05
APP BY	P. FLASKERUD	DATE	10/17/05

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SIZE	PART NO.	REV
A	MLP4X4-16-OP-01	1
SCALE NONE	FILE MLP4X4-16-OP-01-RI.DWG	SHEET 1 OF 1

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